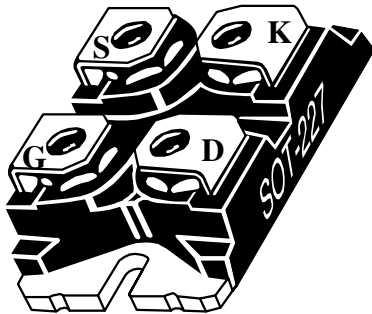
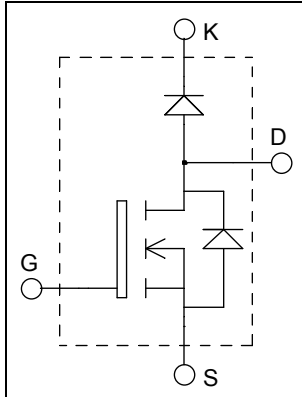


**ISOTOP<sup>®</sup> Boost chopper  
Super Junction  
MOSFET Power Module**

**$V_{DSS} = 600V$**   
 **$R_{DSon} = 45m\Omega \text{ max @ } T_j = 25^\circ C$**   
 **$I_D = 52A \text{ @ } T_c = 25^\circ C$**



### Application

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction
- Brake switch

### Features

- **COOLMOS<sup>®</sup>** Power Semiconductors
  - Ultra low  $R_{DSon}$
  - Low Miller capacitance
  - Ultra low gate charge
  - Avalanche energy rated
- ISOTOP<sup>®</sup> Package (SOT-227)
- Very low stray inductance
- High level of integration

### Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of  $V_{CEsat}$
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_{DSS}$	Drain - Source Breakdown Voltage	600	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	52
		$T_c = 80^\circ C$	38
$I_{DM}$	Pulsed Drain current	130	
$V_{GS}$	Gate - Source Voltage	$\pm 20$	V
$R_{DSon}$	Drain - Source ON Resistance	45	$m\Omega$
$P_D$	Maximum Power Dissipation	$T_c = 25^\circ C$	290
$I_{AR}$	Avalanche current (repetitive and non repetitive)	15	A
$E_{AR}$	Repetitive Avalanche Energy	3	mJ
$E_{AS}$	Single Pulse Avalanche Energy	1900	

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 600V$   $T_j = 25^\circ\text{C}$			250	$\mu\text{A}$
		$V_{GS} = 0V, V_{DS} = 600V$   $T_j = 125^\circ\text{C}$			500	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 22.5A$		40	45	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 3\text{mA}$	2.1	3	3.9	V
$I_{GSS}$	Gate – Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{iss}$	Input Capacitance	$V_{GS} = 0V ; V_{DS} = 25V$ $f = 1\text{MHz}$		7.2		nF
$C_{oss}$	Output Capacitance			8.5		
$Q_g$	Total gate Charge	$V_{GS} = 10V$ $V_{Bus} = 300V$ $I_D = 49A$		150		nC
$Q_{gs}$	Gate – Source Charge			34		
$Q_{gd}$	Gate – Drain Charge			51		
$T_{d(on)}$	Turn-on Delay Time	<b>Inductive Switching (<math>125^\circ\text{C}</math>)</b> $V_{GS} = 10V$ $V_{Bus} = 400V$ $I_D = 49A$ $R_G = 5\Omega$		21		ns
$T_r$	Rise Time			30		
$T_{d(off)}$	Turn-off Delay Time			100		
$T_f$	Fall Time			45		
$E_{on}$	Turn-on Switching Energy	<b>Inductive switching @ <math>25^\circ\text{C}</math></b> $V_{GS} = 10V ; V_{Bus} = 400V$ $I_D = 49A ; R_G = 5\Omega$		675		$\mu\text{J}$
$E_{off}$	Turn-off Switching Energy			520		
$E_{on}$	Turn-on Switching Energy	<b>Inductive switching @ <math>125^\circ\text{C}</math></b> $V_{GS} = 10V ; V_{Bus} = 400V$ $I_D = 49A ; R_G = 5\Omega$		1100		$\mu\text{J}$
$E_{off}$	Turn-off Switching Energy			635		
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V, I_S = -49A$		0.9	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_S = -49A$ $V_R = 400V$ $di_s/dt = 100A/\mu\text{s}$		600		ns
$Q_{rr}$	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		17	

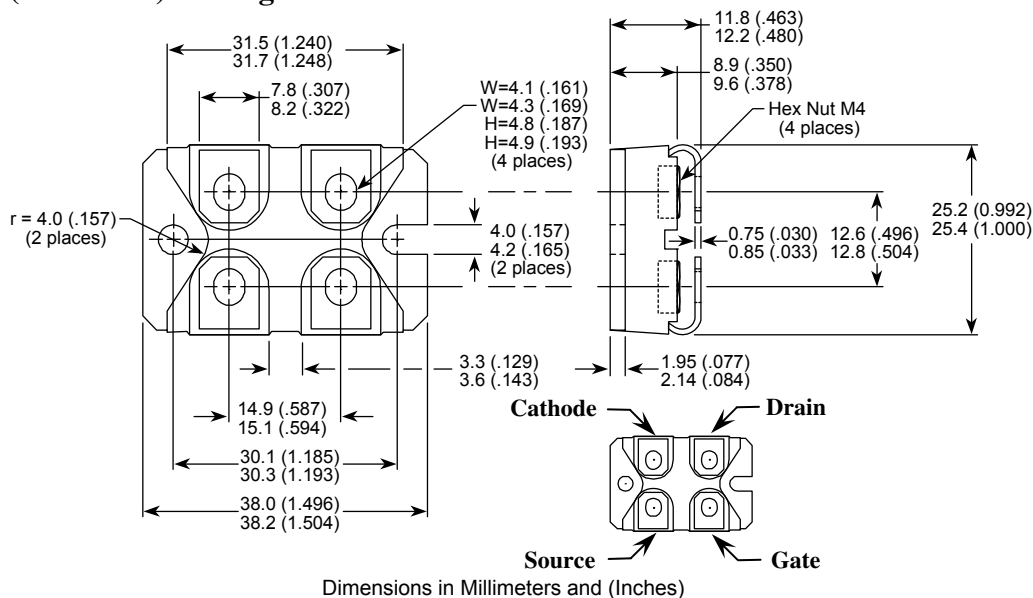
## Chopper diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$V_{RRM}$	Max. Peak Repetitive Reverse Voltage		600			V	
$V_F$	Diode Forward Voltage	$I_F = 30A$		1.8	2.2	V	
		$I_F = 60A$		2			
		$I_F = 30A$	$T_j = 125^\circ C$		1.3		
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600V$	$T_j = 25^\circ C$		100	$\mu A$	
			$T_j = 125^\circ C$		500		
$C_T$	Junction Capacitance	$V_R = 200V$		36		pF	
$t_{rr}$	Reverse Recovery Time	$I_F = 1A, V_R = 30V$ $di/dt = 100A/\mu s$	$T_j = 25^\circ C$		22	ns	
				$T_j = 25^\circ C$			25
				$T_j = 125^\circ C$			160
$I_{RRM}$	Maximum Reverse Recovery Current	$I_F = 30A$ $V_R = 400V$ $di/dt = 200A/\mu s$	$T_j = 25^\circ C$		3	A	
				$T_j = 125^\circ C$			6
				$T_j = 25^\circ C$			35
$Q_{rr}$	Reverse Recovery Charge		$T_j = 25^\circ C$		480	nC	
				$T_j = 125^\circ C$			480
$t_{rr}$	Reverse Recovery Time	$I_F = 30A$	$T_j = 125^\circ C$		85	ns	
$Q_{rr}$	Reverse Recovery Charge	$V_R = 400V$			920	nC	
$I_{RRM}$	Maximum Reverse Recovery Current	$di/dt = 1000A/\mu s$			20	A	

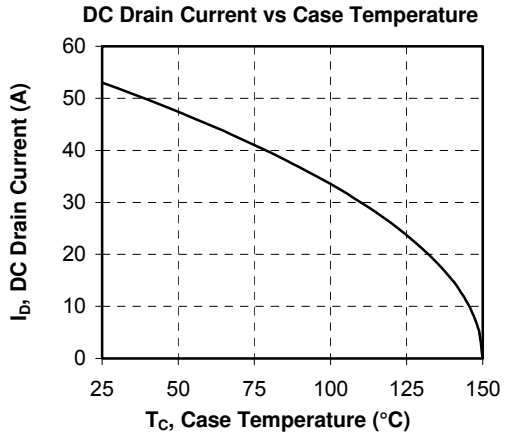
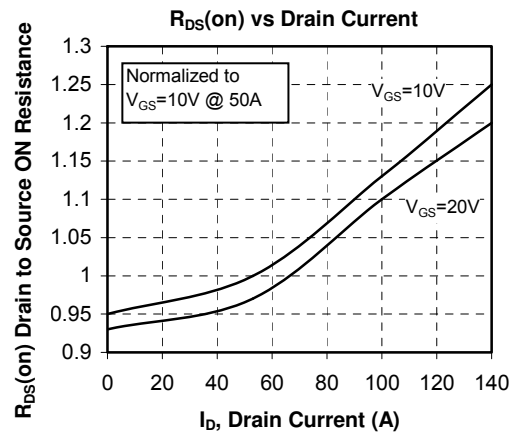
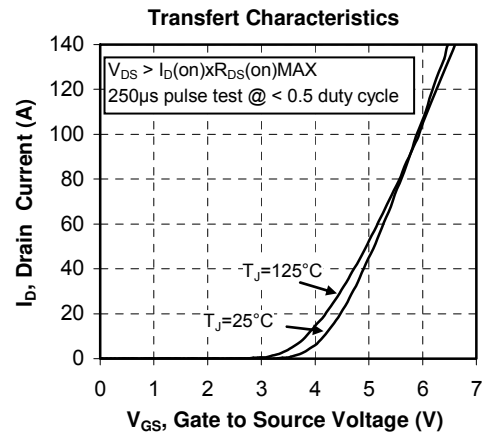
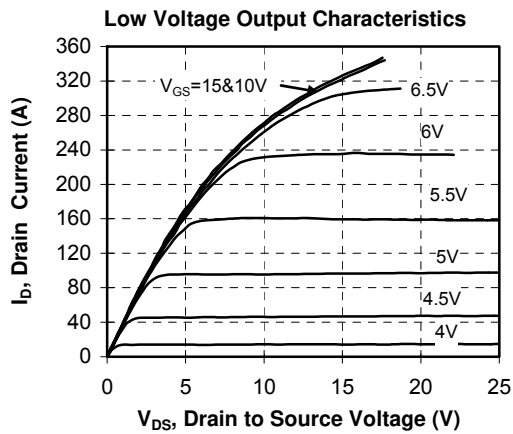
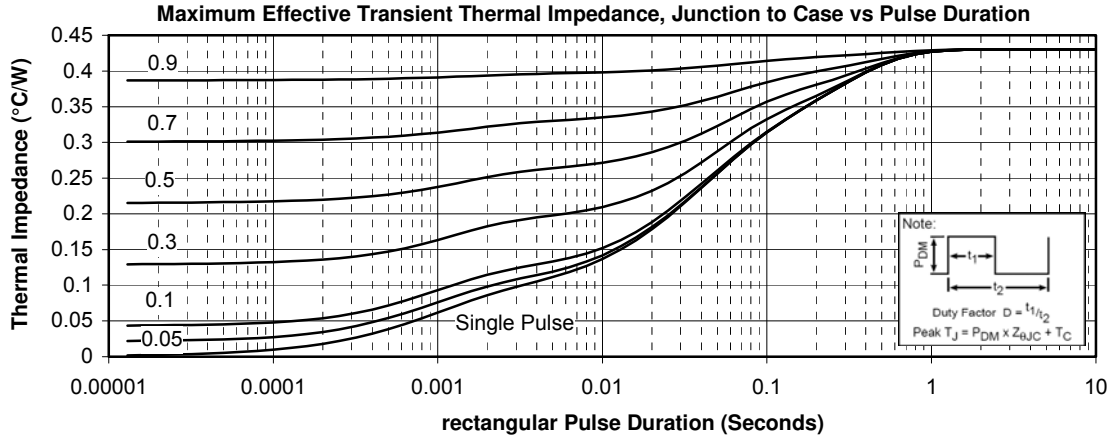
## Thermal and package characteristics

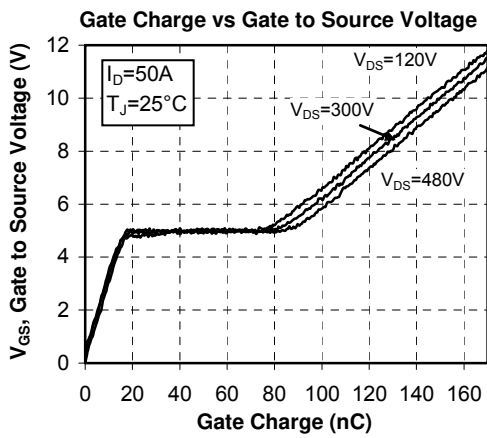
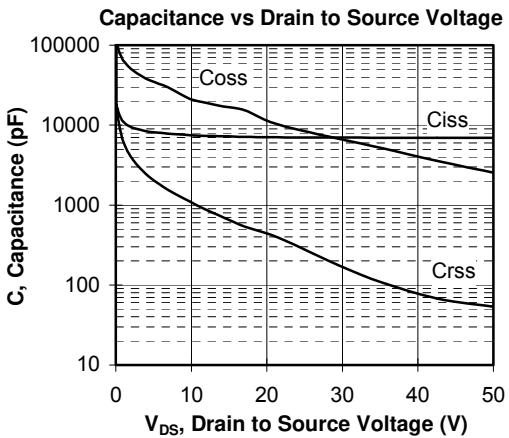
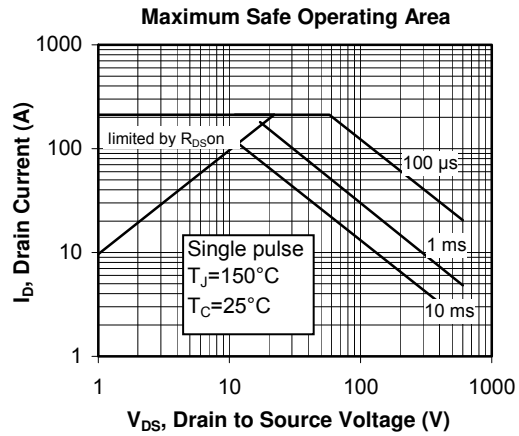
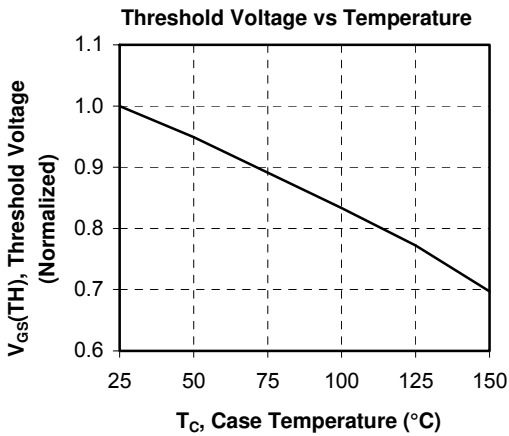
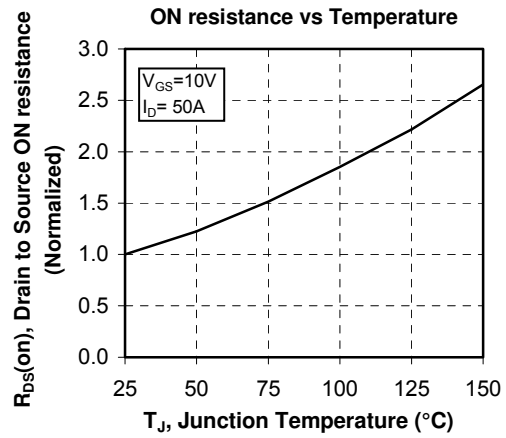
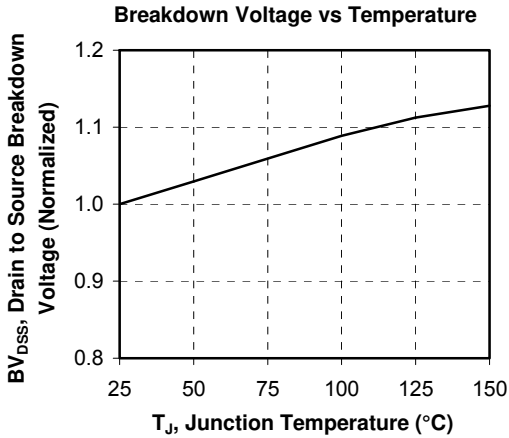
Symbol	Characteristic	Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance	CoolMos		0.43	$^\circ C/W$
		Diode		1.1	
$R_{thJA}$	Junction to Ambient (IGBT & Diode)			20	$^\circ C/W$
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case $t = 1$ min, $I_{isol} < 1mA$ , 50/60Hz	2500			V
$T_J, T_{STG}$	Storage Temperature Range	-40		150	$^\circ C$
$T_L$	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	$^\circ C$
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

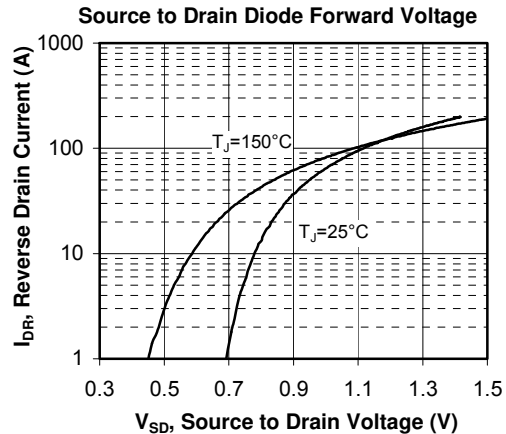
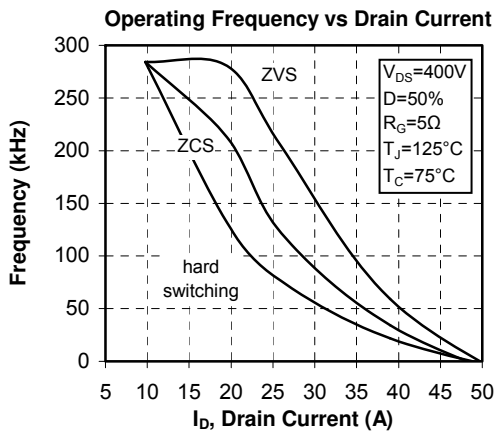
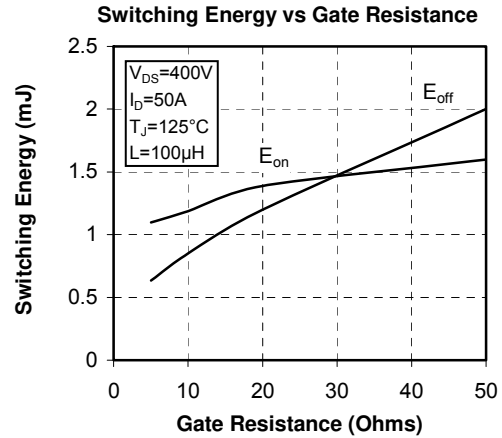
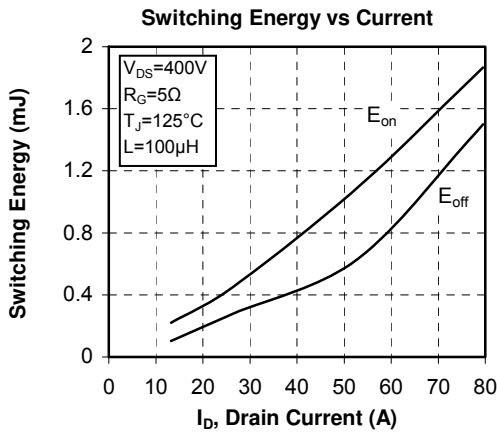
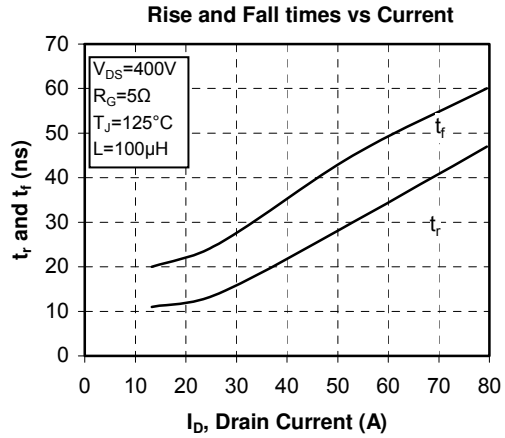
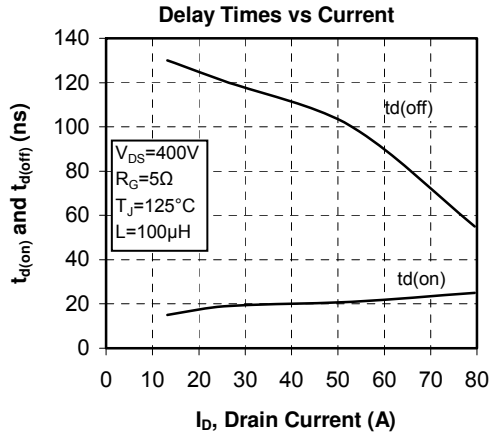
## SOT-227 (ISOTOP<sup>®</sup>) Package Outline



## Typical Performance Curve







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